

- 868.6 MHz Low-loss SAW Filter
- Surface Mount 3.0 x 3.0 mm Package
- Complies with Directive 2002/95/EC (RoHS)

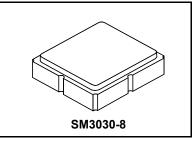


Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	15	dBm
DC Voltage on any Non-ground Terminal	5	V
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

SF2425E

868.6 MHz SAW Filter



Electrical Characteristics

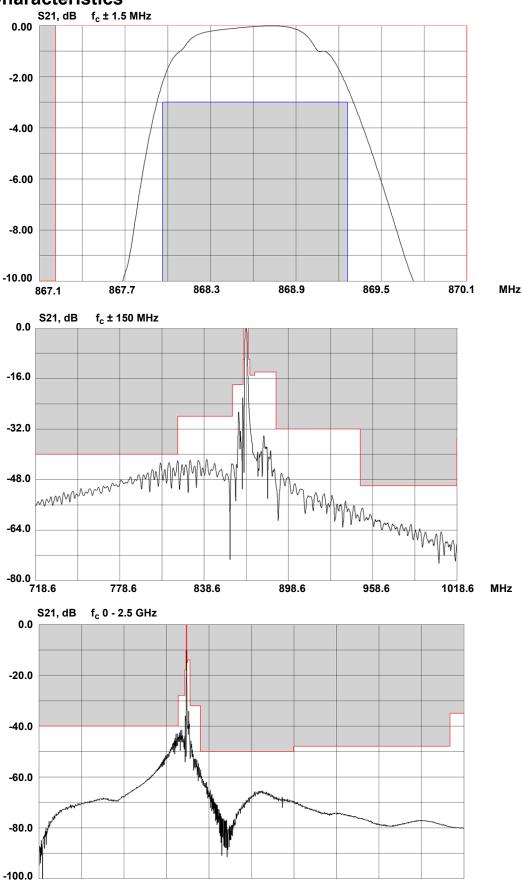
Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	f _C			868.6		MHz
Minimum Insertion Loss, incl. loss of matching elements	IL _{MIN}	1		2.65	3.50	dB
3dB BW			1.3	1.5		MHz
Attenuation (Relative to IL _{min})		1				
10.00 to 820.00 MHz			40	45		
820.00 to 859.00 MHz			28	33		
859.00 to 866.60 MHz			18	23		
866.60 to 867.20 MHz			10	14		
870.40 to 871.40 MHz			10	20		
871.40 to 875.00 MHz			15	19		dB
875.00 to 890.00 MHz			14	17		
890.00 to 950.00 MHz			32	36		
950.00 to 1500.00 MHz			50	55		
1500.00 to 2420.00 MHz			48	65		
2420.00 to 2500.00 MHz			-35	-40		
Case Style		SM3030-8 3.0 x 3.0 mm Nominal Footprint				
Lid Symbolization, Y=year, WW=week, S=shift, dot=pin 1 indicator		8J, <u>YWWS</u>				
INPUT Z _{in} = R _{in} C _{in}				386 1.6		OllnE
OUTPUT Z _{out} = R _{out} C _{out}				371 1.8		Ω∥pF

W

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. **NOTES:**

- The matching circuit is real by actual passive components.
 0805 Coillcraft CS series chip is used for inductor.
 0402 MuRata GRM series is used for capacitor.
- 2. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

Frequency Characteristics



500.0

1000.0

1500.0

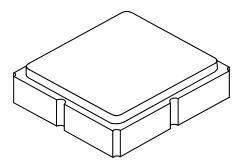
2000.0

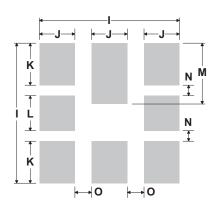
2500.0

MHZ

SM3030-8 Case

8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint





PCB Land Pattern Top View

Electrical Connections

Connection	Terminals
Input Ground or Input	1
Input or Input Ground	2
Output Ground or Output	5
Output or Output Ground	6
Ground	3, 4, 7, 8

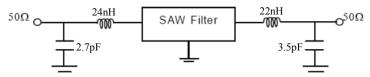
Case and PCB Footprint Dimensions

Dimension	mm			Inches			
Dilliension	Min	Nom	Max	Min	Nom	Max	
Α	2.87	3.00	3.13	0.113	0.118	0.123	
В	2.87	3.00	3.13	0.113	0.118	0.123	
С	-	-	1.10	-	-	0.043	
D	0.79	0.92	1.05	0.031	0.036	0.041	
E	0.62	0.75	0.88	0.024	0.029	0.034	
F	0.47	0.60	0.73	0.018	0.024	0.029	
G	0.47	0.60	0.73	0.018	0.024	0.029	
Н	1.07	1.20	1.33	0.042	0.047	0.052	
1		3.19			0.126		
J		0.81			0.032		
K		0.96			0.038		
L		0.81			0.032		
M		1.39			0.055		
N		0.23			0.009		
0		0.38			0.015		

Case Materials

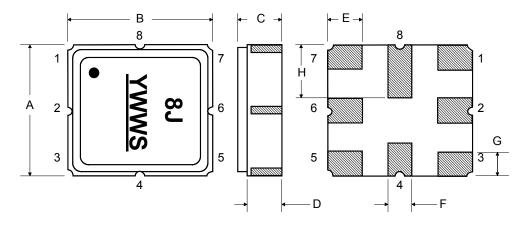
Materials				
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al ₂ O ₃ Ceramic			
Pb Free				

Test Circuit

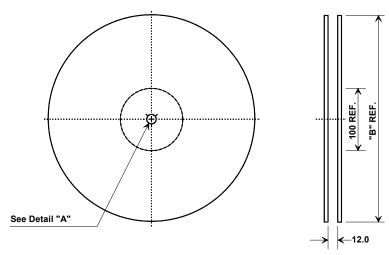


TOP VIEW

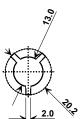
BOTTOM VIEW



Tape and Reel Specifications



"	'B"	Quantity Per Reel
Inches	millimeters	quantity : or recor
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions				
Ao	3.3 ± 1 mm			
Во	3.3 ± 1 mm			
Ko	1.4 ± 1 mm			
Pitch	4.0 mm			
W	12.0 ± 3 mm			

